TRADEMARK ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

ETAS ID: TM452781

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	SECURITY INTEREST

CONVEYING PARTY DATA

Name	Formerly	Execution Date	Entity Type
INNOVATIVE MICRO TECHNOLOGY, INC.		10/13/2017	Corporation: DELAWARE

RECEIVING PARTY DATA

Name:	AGILITY CAPITAL II, LLC
Street Address:	812 Anacapa Street, Suite A
City:	Santa Barbara
State/Country:	CALIFORNIA
Postal Code:	93101
Entity Type:	Limited Liability Company: CALIFORNIA

PROPERTY NUMBERS Total: 3

Property Type	Number	Word Mark
Registration Number:	3757243	CENFIRE
Registration Number:	2770946	IMT
Registration Number:	2673392	INNOVATIVE MICRO TECHNOLOGY

CORRESPONDENCE DATA

Fax Number: 6506440520

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 6506483802
Email: patty@pattycheng.com
Correspondent Name: Patty Cheng
Address Line 1: 2625 MIDDLEFIELD ROAD, SUITE 215
Address Line 4: Palo Alto, CALIFORNIA 94306

NAME OF SUBMITTER:	Patty Cheng
SIGNATURE:	/s/ Patty Cheng
DATE SIGNED:	11/30/2017

Total Attachments: 6
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INTELLECTUAL PROPERTY SECURITY AGREEMENT

This **INTELLECTUAL PROPERTY SECURITY AGREEMENT** is entered into as of October 13 2017 by and between **INNOVATIVE MICRO TECHNOLOGY, INC.**, a Delaware corporation ("**Grantor**") and **AGILITY CAPITAL II, LLC**, a California limited liability company ("**Lender**").

RECITALS

Lender has agreed to make certain advances of money and to extend certain financial accommodations to Grantor in the amounts and manner set forth in that certain Loan Agreement by and between Lender and Grantor (as amended from time to time, the "**Loan Agreement**") dated on or about the date hereof. Capitalized terms used herein have the meaning assigned in the Loan Agreement. Lender is willing to make the financial accommodations to Grantor, but only upon the condition, among others, that Grantor shall grant to Lender a security interest in all of Grantor's right title, and interest in, to and under all of the Collateral whether presently existing or hereafter acquired.

NOW, THEREFORE, Grantor agrees as follows:

AGREEMENT

To secure performance of Grantor's obligations under the Loan Agreement, Grantor grants to Lender a security interest in all of Grantor's right, title and interest in Grantor's intellectual property (including without limitation those Copyrights, Patents and Trademarks listed on Exhibits A, B and C hereto), including without limitation all proceeds thereof (such as, by way of example but not by way of limitation, license royalties and proceeds of infringement suits). This security interest is granted in conjunction with the security interest granted to Lender under the Loan Agreement. Each right, power and remedy of Lender provided for herein shall not preclude the simultaneous or later exercise by Lender of any or all other rights, powers or remedies.

This Agreement may be executed in two or more counterparts, each of which shall be deemed an original, but all of which together shall constitute one instrument. In the event that any signature is delivered by facsimile transmission or by e-mail delivery of a ".pdf" format data file, such signature shall create a valid and binding obligation of the party executing (or on whose behalf such signature is executed) with the same force and effect as if such facsimile or ".pdf" signature page were an original hereof.

[SIGNATURE PAGE FOLLOWS]

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10/13

IN WITNESS WHEREOF, the parties have caused this Intellectual Property Security Agreement to be duly executed as of the first date written above.

Address of Grantor:

75 Robin Hill Road
Goleta, CA 93117

INNOVATIVE MICRO TECHNOLOGY, INC.

By: Craig H Ensley
Name: CRAIG H ENSLEY
Title: CEO

Address of Lender:

812 Anacapa Street, Suite A
Santa Barbara, CA 93101

AGILITY CAPITAL II, LLC

By: [signature]
Name: DANIEL CORRY
Title: MANAGING MEMBER

EXHIBIT A

Copyrights

If None, check this box: ☑

Title	Registration Number	Registration Date

EXHIBIT B
Patents

Title	Serial No./ Patent Number	Application / Issue Date
Microfabricated optical apparatus	9,608,731	March 28, 2017
Anodic bonding of dielectric substrates	9,533,877	January 3, 2017
Etching technique for microfabrication substrates	9,493,877	November 15, 2016
Device using glass substrate anodic bonding	9,388,037	July 12, 2016
Solder bump sealing method and device	9,330,874	May 3, 2016
Method for forming through substrate vias with tethers	9,324,613	April 26, 2016
Method using glass substrate anodic bonding	9,315,375	April 19, 2016
Method for forming a microfabricated structure	9,302,905	April 5, 2016
Microfabricated magnetic field transducer with fluxguide	9,274,180	March 1, 2016
Wafer level hermetic bond using metal alloy with raised feature and wetting layer	9,162,878	October 20, 2015
Method and device using silicon substrate to glass substrate anodic bonding	9,156,679	October 13, 2015
Multi-stage cartridge for MEMS particle storing system	8,993,311	March 31, 2015
MEMS particle sorting actuator and method of manufacturing	8,871,500	October 28, 2014
Exothermic activation for high vacuum packaging	8,847,373	September 30, 2014
Cartridge for MEMS particle sorting system	8,822,207	September 2, 2014
Wafer level hermetic bond using metal alloy with keeper layer	8,736,081	May 27, 2014
In-plane electromagnetic MEMS pump	8,690,830	April 8, 2014
Microfabicated electromagnetic actuator with push-pull motion	8,608,700	December 17, 2013
Inductive getter activation for high vacuum packaging	8,558,364	October 15, 2013
Inlaid optical material and method of manufacture	8,541,735	September 24, 2013
Configurable power supply using MEMS switch	8,466,760	June 18, 2013
Plating process and apparatus for through wafer features	8,343,791	January 1, 2013
Method and apparatus for applying thin liquid coatings	8,338,283	December 25, 2012
Wafer level hermetic bond using metal alloy with keeper layer	8,288,211	October 16, 2012
Dual substrate MEMS plate switch and method of manufacture	8,264,307	September 11, 2012
Method of manufacturing a hysteretic MEMS two-dimensional thermal device	8,245,391	August 21, 2012
System and method for providing access to an encapsulated device	8,088,651	January 3, 2012
Wafer bonding material with embedded conductive particles	7,972,683	July 5, 2011
Lid structure for microdevice and method of manufacture	7,968,986	June 28, 2011
Wafer level hermetic bond using metal alloy with raised feature	7,960,208	June 14, 2011
Hysteretic MEMS thermal device and method of manufacture	7,944,113	May 17, 2011
Dual substrate MEMS plate switch and method of manufacture	7,893,798	February 22, 2011
MEMS thermal device with slideably engaged tether and method of manufacture	7,872,432	January 18, 2011
MEMS plate switch and method of manufacture	7,864,006	January 4, 2011
MEMS device using NiMn alloy and method of manufacture	7,812,703	October 12, 2010
Wafer bonding material with embedded rigid particles	7,807,547	October 5, 2010
System and method for forming moveable features on a composite substrate	7,785,913	August 31, 2010
Indented lid for encapsulated devices and method of manufacture	7,759,218	July 20, 2010
MEMS thermal actuator and method of manufacture	7,759,152	July 20, 2010
Singly attached MEMS thermal device and method of manufacture	7,724,121	May 25, 2010
Etching/bonding chamber for encapsulated devices and method of use	7,713,786	May 11, 2010
Contact electrode for microdevices and etch method of manufacture	7,688,167	March 30, 2010
Current-driven device using NiMn alloy and method of manufacture	7,687,304	March 30, 2010
Interconnect structure using through wafer vias and method of fabrication	7,675,162	March 9, 2010

Title	Serial No./ Patent Number	Application / Issue Date
Hysteretic MEMS two-dimensional thermal device and method of manufacture	7,626,311	December 1, 2009
MEMS thermal actuator and method of manufacture	7,622,783	November 24, 2009
Hermetic interconnect structure and method of manufacture	7,582,969	September 1, 2009
Wafer level hermetic bond using metal alloy with raised feature	7,569,926	August 4, 2009
System and method for providing access to an encapsulated device	7,550,778	June 23, 2009
Hysteretic MEMS thermal device and method of manufacture	7,548,145	June 16, 2009
Elastic interface for wafer bonding apparatus	7,533,792	May 19, 2009
Dual substrate electrostatic MEMS switch with hermetic seal and method of manufacture	7,528,691	May 5, 2009
Indented structure for encapsulated devices and method of manufacture	7,462,931	December 9, 2008
Multiple switch MEMS structure and method of manufacture	7,276,991	October 2, 2007
MEMS device trench plating process and apparatus for through hole vias	7,233,048	June 19, 2007
MEMS teeter-totter apparatus with curved beam and method of manufacture	7,210,352	May 1, 2007
Method and apparatus for assembling an array of micro-devices	7,141,080	November 28, 2006
Method and apparatus for assembling an array of micro-devices	7,057,245	June 6, 2006
Low inertia latching microactuator	6,831,380	December 14, 2004
Method and apparatus for assembling an array of micro-devices	6,812,061	November 2, 2004
Optical switch with low inertia micromirror	6,801,681	October 5, 2004
Wafer level method for probing micromechanical devices	6,593,749	July 15, 2003
Microelectromechanical switch with braking algorithm	6,351,201	February 26, 2002
Microfabricated cross flow filter and method of manufacture	11/136552	May 25, 2005
Antistiction MEMS substrate and method of manufacture	11/151415	June 14, 2005
Wafer level hermetic bond using metal alloy	11/211622	August 26, 2005
Compact MEMS thermal device and method of manufacture	11/263912	November 2, 2005
Method and apparatus for curing epoxy-based photoresist using a continuously varying temperature profile	11/364334	March 1, 2006
System and method for forming through wafer vias using reverse pulse plating	11/482944	July 10, 2006
Micromechanical device with gold alloy contacts and method of manufacture	11/785119	April 16, 2007
Gettering material for encapsulated microdevices and method of manufacture	11/819338	June 27, 2007
Deposition/bonding chamber for encapsulated microdevices and method of use	12/007485	January 11, 2008
Removable/disposable apparatus for MEMS particle sorting device	12/149637	May 6, 2008
Wafer level hermetic bond using metal alloy	12/222845	August 18, 2008
Wafer bonding chamber with dissimilar wafer temperatures	13/385214	February 8, 2012
Dual substrate electrostatic mems switch with multiple hinges and method of manufacture	15/060630	March 4, 2016
Thermocompression bonding with raised feature	15/149217	May 9, 2016
Device with separation limiting standoff	15/232871	August 10, 2016
Mems reed switch device	15/237120	August 15, 2016
Microfabricated optical apparatus with integrated turning surface	15/355461	November 18, 2016
Microfabricated optical apparatus	15/408956	January 18, 2017
Through substrate vias using solder bumps	15/415919	January 26, 2017
Microfabricated optical apparatus	15/272481	September 22, 2016
Mems particle sorting actuator and method of manufacture	9,372,185	June 21, 2016
Method for forming through wafer vias	13/987871	September 11, 2013

EXHIBIT C

Trademarks

If None, check this box: ☐

Description	Serial / Registration Number	Application /Registration Date
CENFIRE	3757243	March 9, 2010
CENTURION	77610691	*
IMT	2770946	October 7, 2003
IMT INNOVATIVE MICRO TECHNOLOGY	76267001	*
INNOVATIVE MICRO TECHNOLOGY	2673392	January 7, 2003

*Indicates dead, abandoned or cancelled trademark